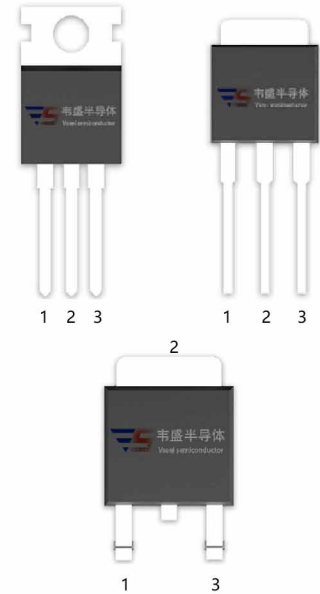


## DESCRIPTION:

With high ability to withstand the shock loading of large current, **VST151-SS** of silicon controlled rectifiers provide high dv/dt rate with strong resistance to electromagnetic interference.



## MAIN FEATURES

Symbol	Value	Symbol
$V_{DRM}/V_{RRM}$	650/800	V
$I_{T(RMS)}$	12	A
$I_{GT}$	$\leq 15$	mA

## ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		$T_{stg}$	-40 - 150	$^{\circ}\text{C}$
Operating junction temperature range		$T_j$	-40 - 150	$^{\circ}\text{C}$
Repetitive peak off-state voltage ( $T_j=25^{\circ}\text{C}$ )		$V_{DRM}$	650/800	V
Repetitive peak reverse voltage ( $T_j=25^{\circ}\text{C}$ )		$V_{RRM}$	650/800	V
RMS on-state current	TO-252-4R ( $T_c=115^{\circ}\text{C}$ )	$I_{T(RMS)}$	12	A
	TO-263 ( $T_c=100^{\circ}\text{C}$ )			
Non repetitive surge peak on-state current ( $F=50\text{Hz}$ $t_p=10\text{ms}$ )		$I_{TSM}$	120	A
Non repetitive surge peak on-state current ( $F=60\text{Hz}$ $t_p=8.3\text{ms}$ )		$I_{TSM}$	132	A
$I^2t$ value for fusing ( $t_p=10\text{ms}$ )		$I^2t$	72	$\text{A}^2\text{s}$
Repetitive rate of rise of on-state current ( $I_G=2 \times I_{GT}$ )		$dI_T/dt$	50	$\text{A}/\mu\text{s}$
Peak gate current		$I_{GM}$	2	A

Peak gate power	$P_{GM}$	5	W
Average gate power dissipation	$P_{G(AV)}$	0.5	W

### ELECTRICAL CHARACTERISTICS ( $T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Test Condition	Value			Unit
		MIN.	TYP.	MAX.	
$I_{GT}$	$V_D=12\text{V } R_L=33\Omega$	-	4	15	mA
$V_{GT}$		-	0.75	1.5	V
$V_{GD}$	$V_D=V_{DRM} T_j=150^{\circ}\text{C } R_L=3.3\text{K}\Omega$	0.2	-	-	V
$I_L$	$I_G=1.2I_{GT}$	-	12	40	mA
$I_H$	$I_T=500\text{mA}$	-	12	30	mA
$dV/dt$	$V_D=540\text{V}$ Gate Open $T_j=150^{\circ}\text{C}$	50	-	-	$\text{V}/\mu\text{s}$
$dV/dt$	$V_D=436\text{V}$ Gate Open $T_j=150^{\circ}\text{C}$	80	-	-	$\text{V}/\mu\text{s}$
$t_{on}$	$I_{GT}=20\text{mA } I_A=100\text{mA } I_R=10\text{mA}$ $T_j=25^{\circ}\text{C}$	-	2	-	$\mu\text{s}$
$t_{off}$		-	30	-	$\mu\text{s}$
$R_d$	Dynamic resistance $T_j=125^{\circ}\text{C}$	-	-	35	$\text{m}\Omega$

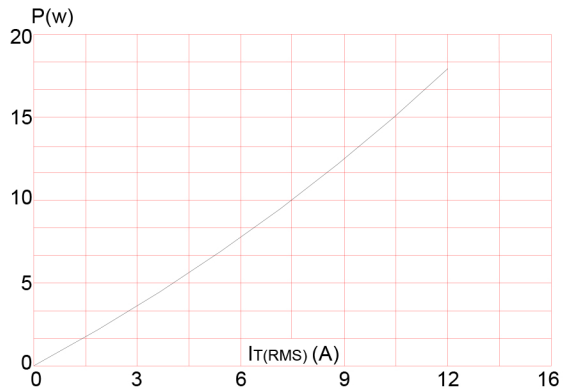
### STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
$V_{TM}$	$I_{TM}=23\text{A } t_p=380\mu\text{s}$	$T_j=25^{\circ}\text{C}$	1.6	V
$I_{DRM}$	$V_D=V_{DRM} V_R=V_{RRM}$	$T_j=25^{\circ}\text{C}$	10	$\mu\text{A}$
$I_{RRM}$		$T_j=150^{\circ}\text{C}$	1	mA

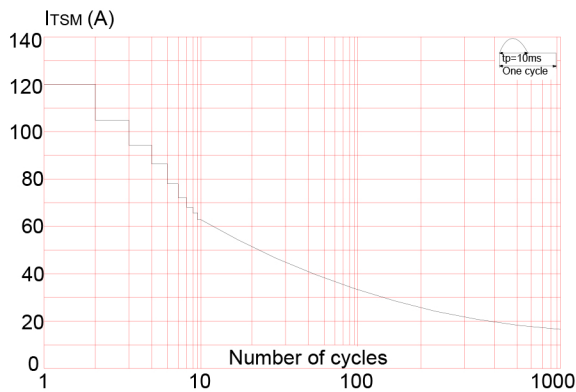
### THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	TO-252-4R	1.3	$^{\circ}\text{C}/\text{W}$
		TO-263	2.0	
$R_{th(j-a)}$	Junction to ambient	TO-252-4R	70	
		TO-263	45	

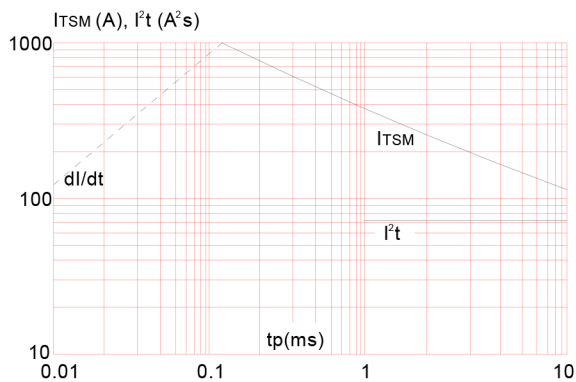
**FIG.1:** Maximum power dissipation versus RMS on-state current



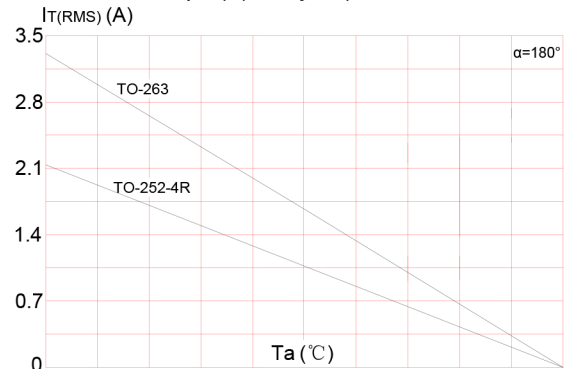
**FIG.3:** Surge peak on-state current versus number of cycles



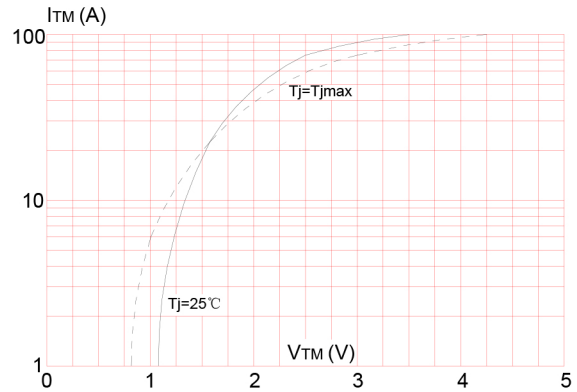
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10\text{ms}$ , and corresponding value of  $I^2t$  ( $di/dt < 50\text{A}/\mu\text{s}$ )



**FIG.2:** RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness:  $35\mu\text{m}$ ) (full cycle)



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature

